

SOT400-1

plastic shrink dual in-line package; 56 leads (600 mil)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SDIP56
Package type industry code	SDIP56
Package style descriptive code	SDIP (shrink dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	51.6	-	52	52.4	mm
E	package width	13.6	-	13.8	14	mm
A	seated height	[tbd]	-	5.08	5.08	mm
A ₂	package height	[tbd]	-	3.85	4	mm
n ₂	actual quantity of termination	-	-	56	-	



2. Package outline

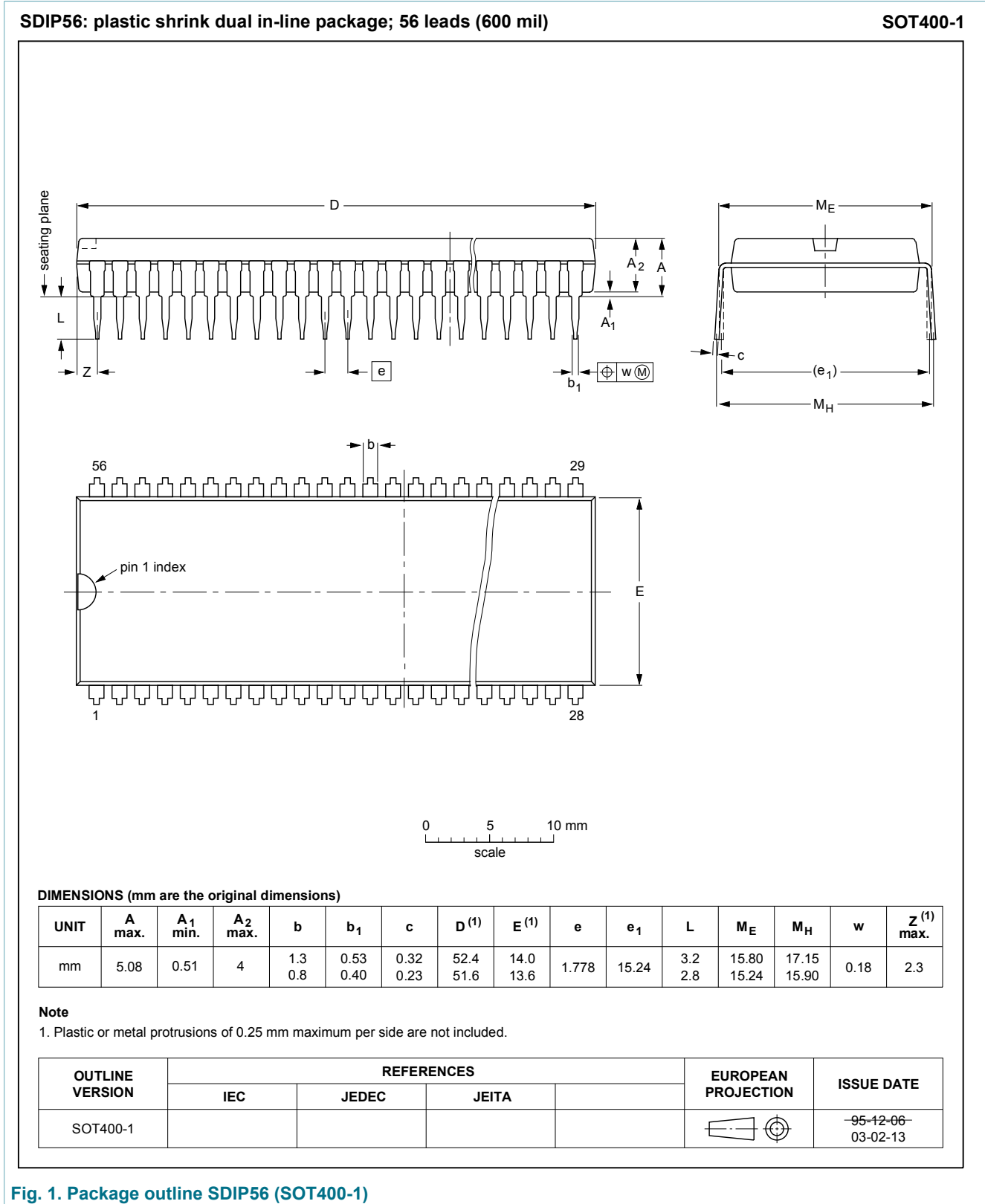


Fig. 1. Package outline SDIP56 (SOT400-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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